

INTERNATIONAL STANDARD

IEC 61189-6

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**Test methods for electrical materials,
interconnection structures and assemblies –**

**Part 6:
Test methods for materials used
in manufacturing electronic assemblies**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHODS FOR ELECTRICAL MATERIALS,
INTERCONNECTION STRUCTURES AND ASSEMBLIES –**

**Part 6: Test methods for materials used
in manufacturing electronic assemblies**

FOREWORD

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International Standard IEC 61189-6 has been prepared by IEC technical committee 91: Electronic assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/593/FDIS	91/610/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

This standard should be used in conjunction with the following parts of IEC 61189, under the main title *Test methods for electrical materials, interconnection structures and assemblies*:

Part 1: General test methods and methodology

Part 2: Test methods for materials for interconnection structures

Part 3: Test methods for interconnection structures (printed boards)

Part 4: Test methods for electronic components assembling characteristics

Part 5: Test methods for printed board assemblies,

and also the following standard:

IEC 60068: Environmental testing

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

INTRODUCTION

IEC 61189 relates to test methods for printed boards and printed board assemblies, as well as related materials or component robustness, irrespective of their method of manufacture.

The IEC 61189 series is divided into separate parts, covering information for the designer and the test methodology engineer or technician. Each part has a specific focus; methods are grouped according to their application and numbered sequentially as they are developed and released.

In some instances test methods developed by other TCs (e.g. TC 104) have been reproduced from existing IEC standards in order to provide the reader with a comprehensive set of test methods. When this situation occurs, it will be noted on the specific test method; if the test method is reproduced with minor revision, those paragraphs that are different are identified.

This part of IEC 61189 contains test methods for evaluating materials used in manufacturing electronic assemblies. The methods are self-contained, with sufficient detail and description so as to achieve uniformity and reproducibility in the procedures and test methodologies.

The tests shown in this standard are grouped according to the following principles:

- P: preparation/conditioning methods
- V: visual test methods
- D: dimensional test methods
- C: chemical test methods
- M: mechanical test methods
- E: electrical test methods
- N: environmental test methods
- X: miscellaneous test methods

To facilitate reference to the tests, to retain consistency of presentation, and to provide for future expansion, each test is identified by a number (assigned sequentially) added to the prefix (group code) letter showing the group to which the test method belongs.

The test method numbers have no significance with respect to an eventual test sequence; that responsibility rests with the relevant specification that calls for the method being performed. The relevant specification, in most instances, also describes pass/fail criterion.

The letter and number combinations are for reference purposes, to be used by the relevant specification. Thus "6C02" represents the chemical test method described in this "Part 6" of IEC 61189. In this example, 6 is the part of IEC standard (61189-6), C is the group of methods, and 02 is the test number.

TEST METHODS FOR ELECTRICAL MATERIALS, INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 6: Test methods for materials used in manufacturing electronic assemblies

1 Scope

This part of IEC 61189 is a catalogue of test methods representing methodologies and procedures that can be applied to materials used in manufacturing electronic assemblies.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-1:1988, *Environmental testing – Part 1: General and guidance*

IEC 61189-1, *Test methods for electrical materials, interconnection structures and assemblies – Part 1: General test methods and methodology*

IEC 61190-1-1, *Attachment materials for electronic assembly – Part 1-1: Requirements for soldering fluxes for high-quality interconnections in electronics assembly*

IEC 61190-1-3, *Attachment materials for electronic assembly – Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications*

ISO 9001, *Quality management systems – Requirements*

ISO 9455 (all parts), *Soft soldering fluxes – Test methods*